

## **AMENDMENTS TO THE CLAIMS**

This listing of claims will replace all prior versions, and listings, of claims in the application:

### **LISTING OF CLAIMS:**

1. (Canceled)
2. (Previously Presented) The manufacturing method according to claim 15, wherein the increasing comprises disposing a casing comprising at least one bottom half-shell at least under the contact pads.
3. (Previously Presented) The manufacturing method according to claim 2, further comprising interfitting the bottom half-shell with a top half-shell covering a zone of the microcircuit that lies outside the contact pads.
4. (Previously Presented) The manufacturing method according to claim 15, wherein the increasing comprises inserting the microcircuit into a shell having an access on a rear edge.
5. (Previously Presented) The manufacturing method according to claim 15, wherein the increasing comprises forming an overmolded portion over the microcircuit.

6. (Previously Presented) The manufacturing method according to claim 2, further comprising fastening the microcircuit to the bottom half-shell.

7. (Previously Presented) The manufacturing method according to claim 6, wherein the fastening is by adhesive bonding or by tight-fitting cross-wise at least.

8. (Previously Presented) The manufacturing method according to claim 15, wherein the electronic component is disposed at a location offset from a location of the contact pads.

9. (Previously Presented) The manufacturing method according to claim 15, wherein the electronic component is disposed on the same top face of the microcircuit as the contact pads.

10 - 14. (Canceled)

15. (Previously Presented) A method for manufacturing a USB electronic key, comprising cutting out, from a dielectric backing film which has a thickness of less than or equal to 200  $\mu\text{m}$  and carries a plurality of microcircuits, a portion of the dielectric backing film including one of the microcircuits, each microcircuit defining USB-format contact pads and carrying an electronic component connected to the pads; and, in a single operation, increasing the thickness of the cut-out portion of the dielectric backing film including the one of the microcircuits at least in the area of the

contact pads of the one of the microcircuits, so as to have a thickness that conforms to the USB Standard.

16. (Currently Amended) A method for manufacturing a USB electronic key from a dielectric backing film which ~~has a thickness of less than or equal to 200  $\mu$ m~~ and carries a microcircuit, the microcircuit defining USB-format contact pads and carrying an electronic component connected to the pads, the method comprising, in a single operation, increasing the thickness of the dielectric backing film including the microcircuit at least in the area of the contact pads of the microcircuit, so as to have a thickness that conforms to the USB Standard.

17. (Previously Presented) The manufacturing method according to claim 16, wherein the increasing comprises disposing a casing comprising at least one bottom half-shell at least under the contact pads.

18. (Previously Presented) The manufacturing method according to claim 17, further comprising interfitting the bottom half-shell with a top half-shell covering a zone of the microcircuit that lies outside the contact pads.

19. (Previously Presented) The manufacturing method according to claim 16, wherein the increasing comprises inserting the microcircuit into a shell having an access on a rear edge.

20. (Previously Presented) The manufacturing method according to claim 16, wherein the increasing comprises forming an overmolded portion over the microcircuit.

21. (Previously Presented) The manufacturing method according to claim 17, further comprising fastening the microcircuit to the bottom half-shell.

22. (Previously Presented) The manufacturing method according to claim 21, wherein the fastening is by adhesive bonding or by tight-fitting cross-wise at least.

23. (Previously Presented) The manufacturing method according to claim 16, wherein the electronic component is disposed at a location offset from a location of the contact pads.

24. (Previously Presented) The manufacturing method according to claim 16, wherein the electronic component is disposed on the same top face of the microcircuit as the contact pads.

25. (New) The manufacturing method according to claim 16, wherein the dielectric backing film has a thickness of less than or equal to 200  $\mu\text{m}$ .

26. (New) A method for manufacturing a USB electronic key from an insulating substrate which carries a microcircuit, the microcircuit defining USB-format contact pads and carrying an electronic component connected to the pads, the

method comprising, in a single operation, increasing the thickness of the insulating substrate including the microcircuit at least in the area of the contact pads of the microcircuit, so as to have a thickness that conforms to the USB Standard.